

# MPW Shuttle Service 2018

## Schedule

Process	Data and Order to	Tape In <sup>1)</sup>	Samples Out <sup>2)</sup>
<b>0.18 μm HV-CMOS 20V / 25V / 50V <sup>3) 8)</sup></b>			
aH18	ams	22-May-18	14-Dec-18
aH18	ams	26-Nov-18	21-Jun-19
<b>0.18 μm CMOS 1.8V / 5V <sup>3) 8)</sup></b>			
aC18	ams	22-May-18	14-Dec-18
aC18	ams	26-Nov-18	21-Jun-19
<b>0.35 μm HV-CMOS 20V / 50V / 120V (embedded Flash <sup>4)</sup>)</b>			
H35B4D3	ams	19-Feb-18	05-Jun-18
H35B4D3	ams	7-May-18	21-Aug-18
H35B4D3	ams	20-Aug-18	04-Dec-18
H35B4D3	ams	5-Nov-18	19-Feb-19
<b>0.35 μm CMOS 3.3V / 5V (embedded Flash <sup>4)</sup>) and 0.35 μm Opto-CMOS <sup>5)</sup></b>			
C35B4xx <sup>6)</sup>	ams	26-Feb-18	23-May-18
C35B4xx <sup>6) 5) 7)</sup>	Fraunhofer IIS	14-May-18	8-Aug-18
C35B4xx <sup>6)</sup>	ams	13-Aug-18	07-Nov-18
C35B4xx <sup>6) 5) 7)</sup>	Fraunhofer IIS	19-Nov-18	13-Feb-19
<b>0.35 μm SiGe-BiCMOS 3.3V / 5V 2P/4M</b>			
S35D4M5	ams	16-Apr-18	24-Jul-18
S35D4M5	ams	3-Sep-18	11-Dec-18
S35D4M5	ams	18-Dec-18	27-Mar-19
<b>0.30 μm Low VT Ultra Low Noise CMOS 3.3V</b>			
A30B4S3	ams	5-Nov-18	28-Jan-19

Additional MPW Shuttles are scheduled by our partners

**Fraunhofer IIS**  
www.iis.fraunhofer.de

**CMP**  
mycmp.fr

**MEDs Technologies**  
www.meds-tech.com



**Europractice**  
www.europractice-ic.com

**MOSIS**  
www.mosis.com

**TOPPAN**  
www.toptdc.com



**TOPPAN**

### Contacts

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## Services

Technologies available for MPW service					Issue November 2017	
Process	Technology	Voltage Levels		Available Options		
<b>aH18</b>	<b>0.18 μm HV-CMOS</b>	1.8/5V Gates	1.8/5/20/25/50V FETs	RR, RP, NE, PE, QT	6 Metal AM, 1 Poly	
<b>aC18</b>	<b>0.18 μm CMOS</b>	1.8/5V Gates	1.8/5V FETs	RR, RP, NE, PE, QT	6 Metal AM, 1 Poly	
<b>H35</b>	<b>0.35 μm HV-CMOS</b>	3.3/5/20V Gates	3.3/5/20/50/120V FETs	HR, PIP	4 Metal, 2 Poly	
<b>C35</b>	<b>0.35 μm CMOS</b>	3.3/5V Gates	3.3/5 FETs	HR, PIP	4 Metal, 2 Poly	
<b>S35</b>	<b>0.35 μm SiGe-BiCMOS</b>	3.3/5V Gates	3.3/5/12V HBTs	HR, PIP, MIM	4 Metal, 2 Poly	
<b>A30</b>	<b>0.30 μm CMOS</b>	3.3V Gates	3.3V FETs	HR, PIP, Low VT	4 Metal, 2 Poly	

The participation in the ams MPW service includes the delivery of 40 dice.

Process stops, wafer probe tests or wafer shipments are not possible for MPWs.

Additional Services	Comment
<b>Additional Dice</b>	Up to 100 possible from single placement on MPW
<b>Ceramic Packages</b>	10 parts with taped lid
<b>Scoop &amp; Goop Packages</b>	10 parts / availability check necessary at tape in
<b>Plastic Packages</b>	50 parts with up to 84 pins / requires an additional cycle time of 2 to 3 weeks
<b>WLCSP with RDL</b>	WLCSP (Balls 250μm, 400μm min. pitch) with redistribution layer available on request (0.35μm only)
<b>0.35 μm CMOS with Embedded Flash</b>	High reliability EEPROM and Flash with block sizes from 1kx8 to 32kx16 bit
<b>0.35 μm HV-CMOS with Embedded Flash</b>	High reliability EEPROM and Flash with block sizes from 1kx8 - 4kx16 bit
<b>0.35 μm Opto CMOS</b>	Opto process with optional EPI wafer startmaterial and antireflective coating layer

### Notes

The total cycle time includes MPW cluster preparation, wafer manufacturing & back-lapping, dicing, assembling in ceramic or in scoop&goop package.

<sup>1)</sup> Please provide a completed Foundry Service Request Form (ENG-21; s.link below "Technical Information"), when providing a database.

<sup>2)</sup> The Sample Out dates are without obligation.

<sup>3)</sup> Please note that other process options than listed in "Available Options" are only available for single die toolings.

<sup>4)</sup> EEPROM resp. Flash option available on request for every MPW-start in 0.35μm CMOS and 0.35μm HV-CMOS technology.

<sup>5)</sup> Opto option available on request. Opto CMOS process only available for 2 poly / 4 metal.

<sup>6)</sup> Represents different process options in ams Fab B (exception: RF-CMOS, e.g. C35B4M3).

<sup>7)</sup> Opto CMOS process with ARC/BARC

<sup>8)</sup> aC18 and aH18 MPW service is limited to ongoing projects and no production on these processes will be supported.

Disclaimer	Information
<b>No implied offer:</b> The usage of ams design kits and/or libraries or the participation on Multi Project Wafer runs shall not be regarded as an implied offer by ams to subsequently manufacture such integrated circuit. In any case each integrated circuit, which is planned for production, requires an official quotation by ams.	Foundry Support Server: <a href="http://asic.ams.com">asic.ams.com</a> Tape-out form: <a href="#">Foundry Request Form</a> Quote: <a href="#">Online Tool for registered Users</a>

Sample out dates are based on planning data status Nov. 2017. The final sample out dates will be communicated at the MPW start date.

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